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DMB No. 0651-0027 (exp. 6/30/2005) RECORDATION FO	United States Patent and Trademark Of RM COVER SHEET
To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below	
1. Name of conveying party(ies)/Execution Date(s): MASAYUKI YASUMURA	<ol><li>Name and address of receiving party(les)</li></ol>
MASATORI 1ASOMORA	
	Name: SONY CORPORATION
Execution Date(s): March 28, 2006	Internal Address:
Additional name(s) of conveying party(les) attached? Yes X No	-
	Shinagawa-Ku, Tokyo
3. Nature of Conveyance:	141-0001
Assignment Merger	JAPAN
Security Agreement Change of Name	City:
Government Interest Assignment	State:
Executive Order 9424, Confirmatory License	Country: Zip:
Other	Additional name(s) & address(es)
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4. Application or patent number(s):	This document is being filed together with a new application.
A. Patent Application No.(s) 10/534.142	B. Patent No.(s)
Additional numbers attached	? Yes x No
Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Robert B. Cohen	
LERNER, DAVID, LITTENBERG,	
KRUMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00
Internal Address: Atty, Dkt.; SONYJP 3.3-1041	Authorized to be charged by credit card
Street Address: 600 South Avenue West	
andervadices, 800 South Avenue west	Authorized to be charged to deposit account
	Enclosed
	None required (government interest not affecting till
Nty: Westfield	8. Payment Information
State: <u>NJ</u> Zip: 07090	a. Credit Card Last 4 Numbers
Phone Number: (908) 518-6316	Expiration Date
ax Number: (908) 654-0415	b. Deposit Account Number 12-1095
Email Address:cohen@ldlkm.com	Authorized User Name Robert B. Cohen
Signature:	
	April 3, 2006
	April 3, 2006 Date

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## PATENT REEL: 017427 FRAME: 0798

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Docket Number: SONYJP3.3-1041 Sony Reference No.: S03P1481US00

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

## SWITCHING POWER SUPPLY CIRCUIT

for which an International Application was filed on December 19, 2003, PCT/JP2003/016339, designating the United States;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141-0001, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the patents or securing of patents in the United States and countries foreign thereto, and in the respect to the filing of applications for patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: \_\_\_\_\_\_, Filing Date: \_\_\_\_\_\_

This assignment executed on the dates indicated below.

<u>Masayuki YASUMURA</u> Name of First or Sole Inventor

Execution Date of U.S. Patent Application

Kanagawa, Japan Residence of First or Sole Inventor

Masayaki Yasumura

Signature of First or Sole Inventor

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March 28, 2006

Date of this Assignment

PATENT REEL: 017427 FRAME: 0799

**RECORDED: 04/03/2006**